



Material Content Data Sheet



Sales Product Name		1EDI30I12MF		Issued		20. July 2018		
MA#		MA001246590						
Package		PG-DSO-8-51		Weight*		80.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.769	2.20	2.20	22038	22038
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103	
	non noble metal	zinc	7440-66-6	0.033	0.04		411	
	non noble metal	iron	7439-89-6	0.660	0.82		8218	
wire	non noble metal	copper	7440-50-8	26.789	33.37	34.24	333696	342428
	noble metal	gold	7440-57-5	0.228	0.28	0.28	2845	2845
	encapsulation	organic material	carbon black	1333-86-4	0.148	0.18		1838
plastics		epoxy resin	-	4.772	5.94		59435	
	inorganic material	silicondioxide	60676-86-0	44.272	55.17	61.29	551458	612731
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10137	10137
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1186	1186
glue	plastics	acrylic resin	-	0.153	0.19		1900	
	noble metal	silver	7440-22-4	0.541	0.67	0.86	6735	8635
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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